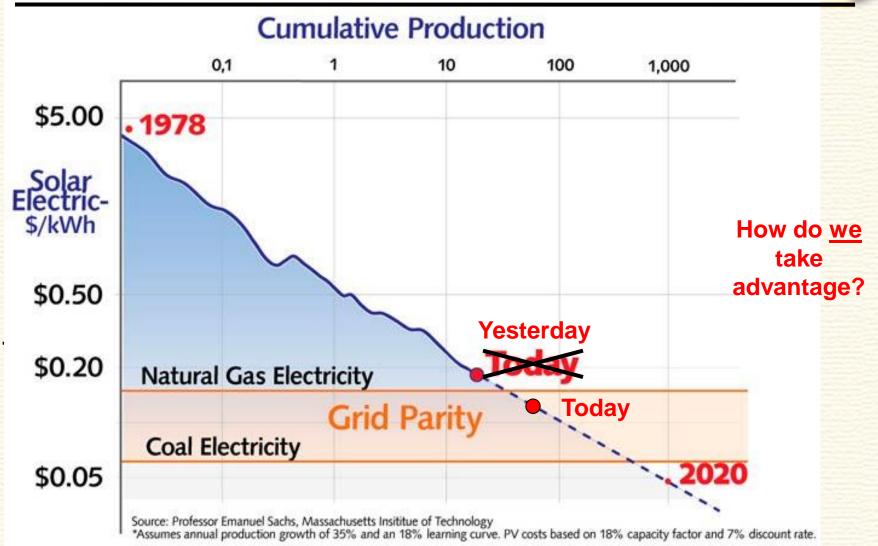


#### **The Question**

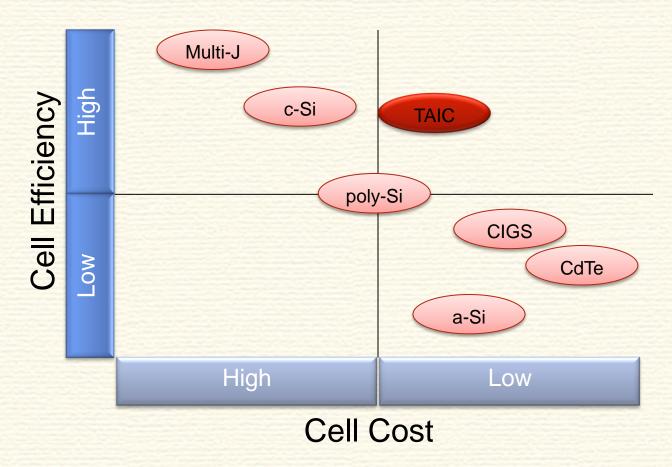




#### **The Pain**



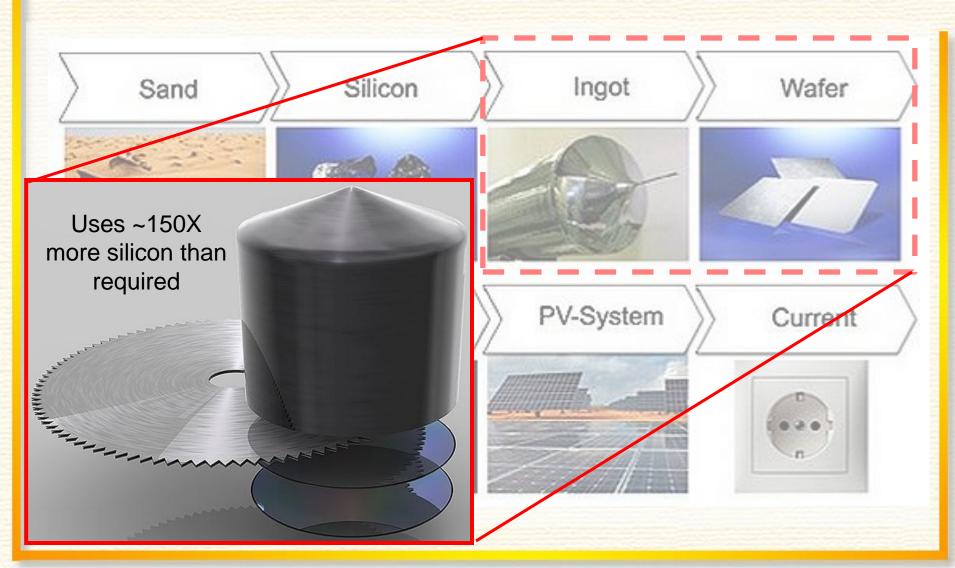
\$/W - Decrease costs while increasing efficiency



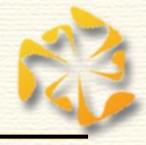
Bottom Line: Wafer level efficiencies at thin-film prices

### Currently

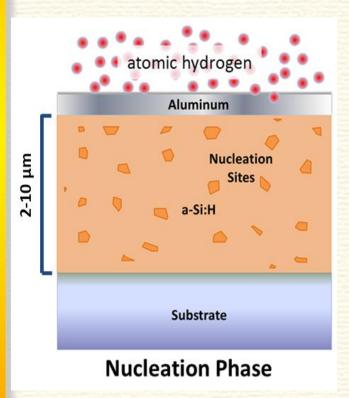




#### **The Solution**



Wafer level efficiencies at thin-film prices

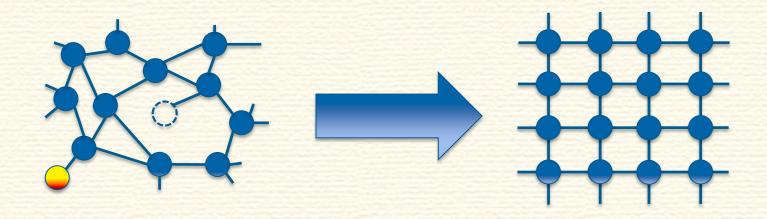


**Double the efficiency** of a-Si cells with practically **zero additional cost** 

## The Technology



Crystallization of amorphous silicon into large grain polysilicon at low temperatures



- "Top-Down Aluminum Induced Crystallization" or TAIC
- Product of \$7M in R&D from NASA, DOD and NSF
- Patented, defensible technology (6 issued 3 pending)

## **Large Grain Polysilicon**



- Polysilicon: uniform crystal grains separated by grain boundaries
- Grain boundaries are the limiting factor
- Our Patented Process
  - Creates 90x larger grains
  - Reduced material thickness
  - Low temperature
  - Verified by UC Irvine labs

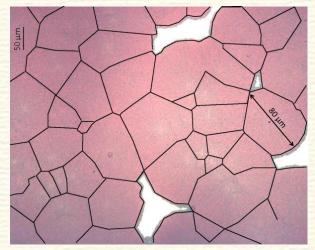
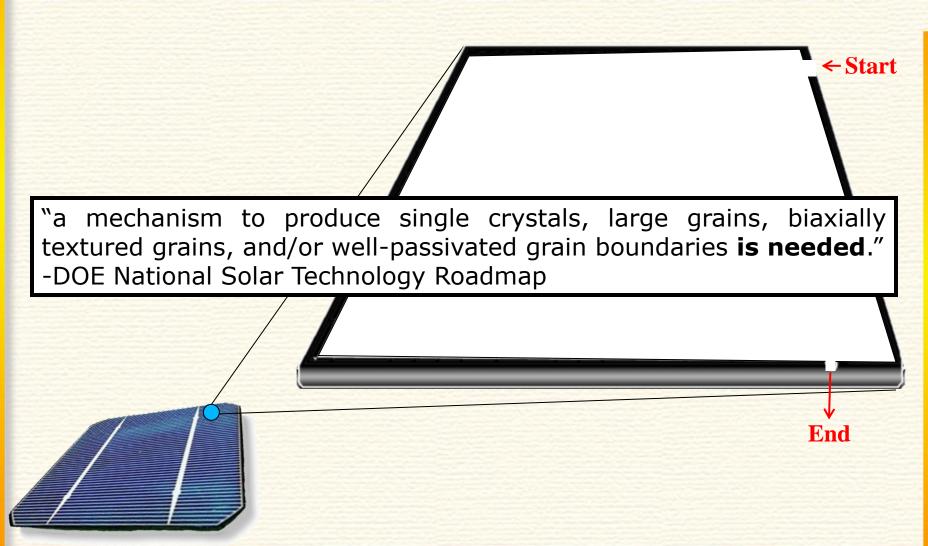


Fig. 1. Poly-Si grains with boundaries visible (magnified ~4000x)

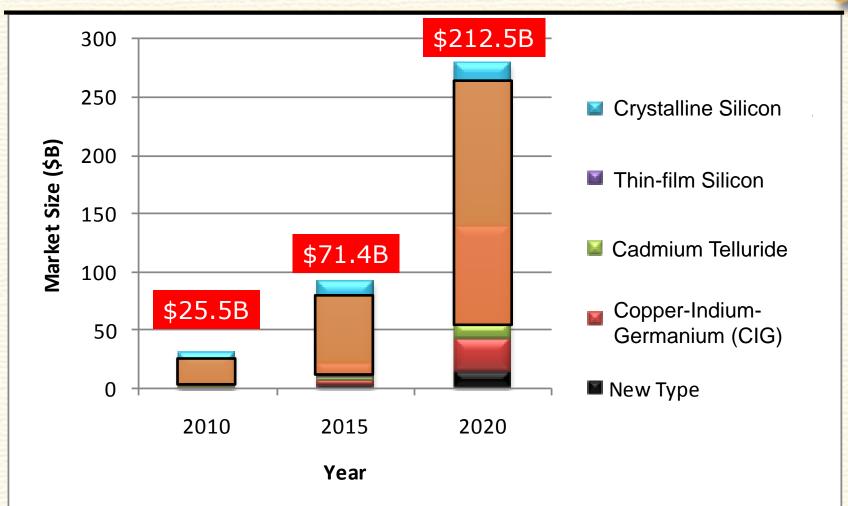
# **Electron's Eye View**





## **Solar Marketplace**

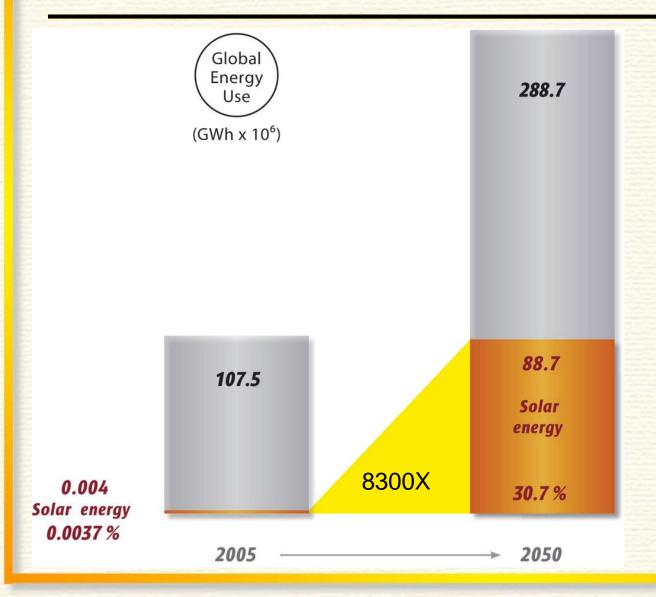




Energy & Capital "A Solar Energy Overview - Forecasts, Trends, and Companies" June 22<sup>nd</sup> 2011 & GlobalData through Energy & Capital 2008

# **The Opportunity**





source: International Energy Agency Forecast (<u>www.iea.org</u>)

# Why not?



